

TPUTTY 506 SERIES - Soft Silicone Putty

Tputty 506 is a soft single part silicone putty thermal gap filler in which no cure is required. This gap filler is ideal for applications where large gap tolerances are present and in which traditional gap filler pads may apply added pressure on components.

This material can be dispensed to fill large and uneven gaps in assemblies.

Tputty 506 has a composition which yields superior thermal performance and super compliancy. This material transfers little to no pressure between interfaces. Tputty 506 is non-abrasive which leads to less wear on dispensing equipment and therefore reduced equipment maintenance/repair costs.



Specifications

Specifications	
Additional Product Description	Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.
Applications	Microprocessors Graphic chips Automotive LED lighting
Color	Turquoise
Freq. Range 2.5 to 8 GHz	DEFAULT
Product Line	Tputty 506 Series
Temperature Range (Max Celsius)	200.00
Temperature Range (Min Celsius)	(-)45.00
Thermal Conductivity	3.50
UL Flammability	V0
Volume Resistivity	Volume Resistivity Del 1.8
_OTHER	Construction and Composition - Fully Cured Ceramic-filled dispensable silicone putty Flow Rate (75 cc taper tip 0.125" orifice 90 psi) - 17.2 cc/min Abrasive ness of Predominant Filler - 2 Minimum Bondline Thickness mm (in) - 0.1 (0.004) Outgassing TML v olume percent - 0.79% Outgassing TML weight percent - 0.46% Coefficient of Volumetric Expansion (CVE) - 680 ppm/K Coefficient of Thermal Expansion (CTE) - 227 ppm/K Tg < -90°C Specific Heat -0.85 J/gK